

500V 5A Dual N-ch Power MOSFET

Description

HM5DN50D is dual VDMOS family that is dramatic reduction in on-resistance and ultra-low gate charge for applications requiring high power density and high efficiency. And it is very robust and RoHS compliant.

Features

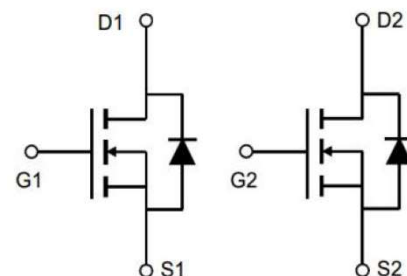
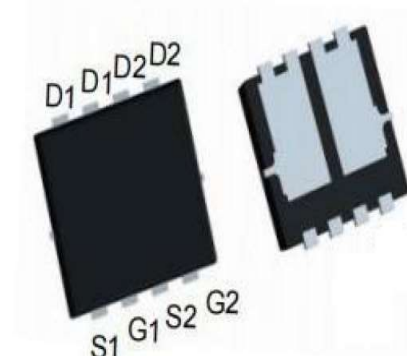
- Typ. $R_{DS(on)}=2.6\Omega@V_{GS}=10V$
- 100% avalanche tested
- Pb-free, Halogen free

Applications

- SMPS
- Charger
- DC-DC



PDFN5*6



Absolute Maximum Ratings ($T_C=25^{\circ}\text{C}$)

Parameter	Symbol	HM5DN50D	Unit
Drain-source voltage	V_{DS}	500	V
Gate-source voltage	V_{GS}	± 30	V
Continuous drain current	I_D	5	A
Pulsed drain current ①	I_{DM}	15	A
Avalanche energy, single pulse ②	E_{AS}	63	mJ
Power dissipation ①	P_D	50	W
Storage temperature	T_{stg}	-55~150	$^{\circ}\text{C}$
Continuous diode forward current	I_S	5	A

Thermal Characteristic

Thermal resistance,junction-to-case	$R_{\theta JC}$	3	$^{\circ}\text{C/W}$
Thermal resistance,junction-to-ambient	$R_{\theta JA}$	62.5	$^{\circ}\text{C/W}$

Electrical Characteristics of MOSFET

				Min.	Typ.	Max.	
Drain-source break down voltage	BV_{DSS}	$I_D=250\mu A$, $V_{GS}=0V$	$T_C=25^\circ C$	500	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$I_D=250\mu A$, $V_{DS}=V_{GS}$	$T_J=25^\circ C$	2.0	3.0	4.0	V
Drain-source leakage current	I_{DSS}	$V_{DS}=500V$, $V_{GS}=0V$	$T_J=25^\circ C$	-	-	1	μA
		$V_{DS}=400V$, $V_{GS}=0V$	$T_J=125^\circ C$	-	-	100	μA
Drain-source on-state resistance	$R_{DS(ON)}$	$V_{GS}=10V$, $I_D=1.5A$ ③	$T_J=25^\circ C$	-	2.6	3.2	Ω

Dynamic Characteristics of MOSFET ($T_C=25^\circ C$)

				Min.	Typ.	Max.	
Input capacitance	C_{iss}	$f=1MHz$, $V_{DS}=25V$, $V_{GS}=0V$	③	-	218	-	pF
Output capacitance	C_{oss}			-	28	-	pF
Reverse transfer capacitance	C_{rss}			-	4	-	pF
Gate to source charge	Q_{gs}	$V_{DS}=480V$		-	0.7	-	nC
Gate to drain charge	Q_{gd}	$I_D=1A$		-	2.7	-	nC
Total gate charge	Q_g	$V_{GS}=10V$		-	4.8	-	nC

Switching Characteristics of MOSFET ($T_C=25^\circ C$)

				Min.	Typ.	Max.	
Turn-off delay time	$t_{d\ off}$	$V_{DD}=300V$, $I_D=3A$, $R_G=25\Omega$	③	-	13	-	ns

Characteristics of Body Diode ($T_C=25^\circ C$)

				Min.	Typ.	Max.	
Forward voltage	V_{SD}	$I_S=3A$, $V_{GS}=0V$, $T_J=25^\circ C$	③	-	-	1.4	V
Reverse recovery time	t_{rr}	$I_f=3A$, $T_J=25^\circ C$	③	-	62	-	ns
Recovery charge	Q_{rr}	$di/dt=100A/\mu s$		-	0.28	-	μC

Note:

1. ID & PD base on maximum allowable junction temperature, test at $T_C=25^\circ C$.
2. Starting $T_J=25^\circ C$, $V_{DD}=50V$, $L=30mH$, $R_G=25\Omega$, $I_{AS}=3.0A$
3. Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$

TYPICAL CHARACTERISTICS

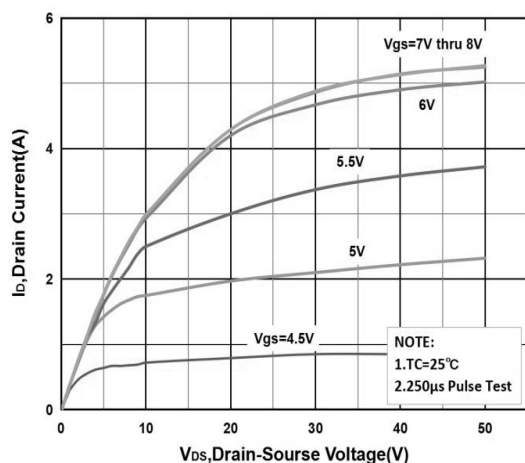


Figure 1. Typical Output Characteristics, $T_c = 25^\circ\text{C}$

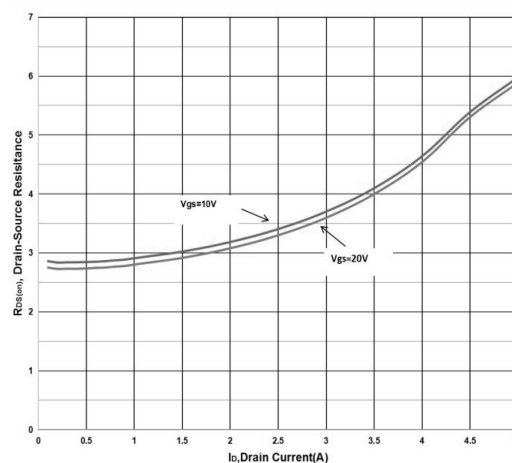


Figure 2. On-Resistance Vs. Drain Current and Gate Voltage

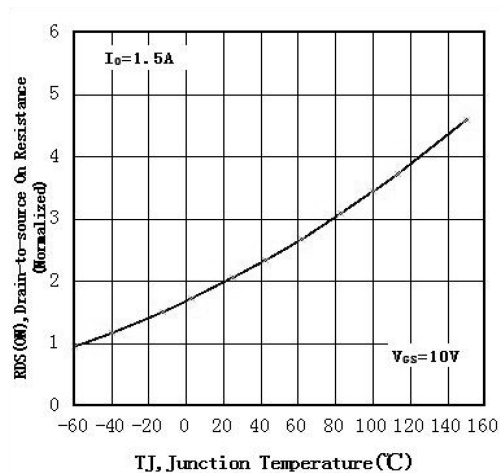


Figure 3. Normalized On-Resistance Vs. Temperature

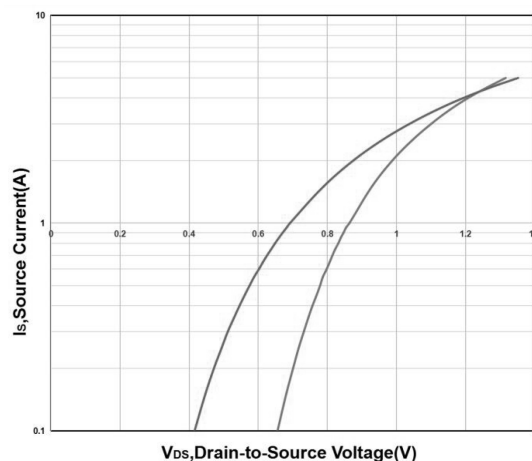


Figure 4. Typical Source-Drain Diode Forward Voltage

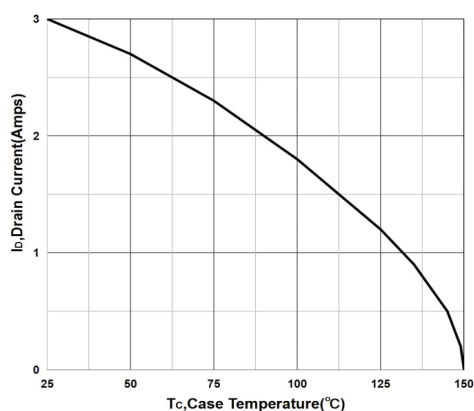


Figure 5. Maximum Drain Current Vs. Case Temperature

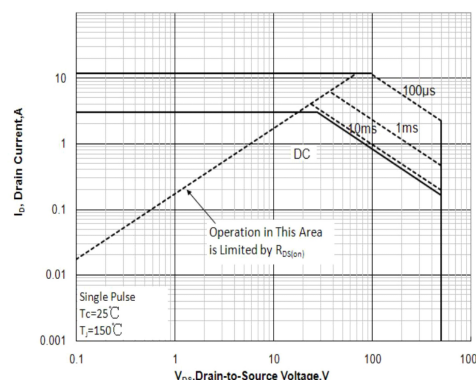
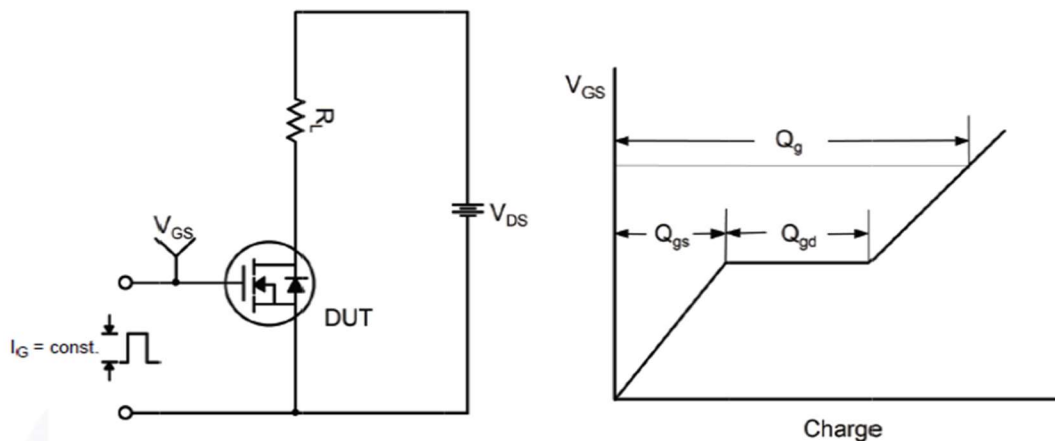
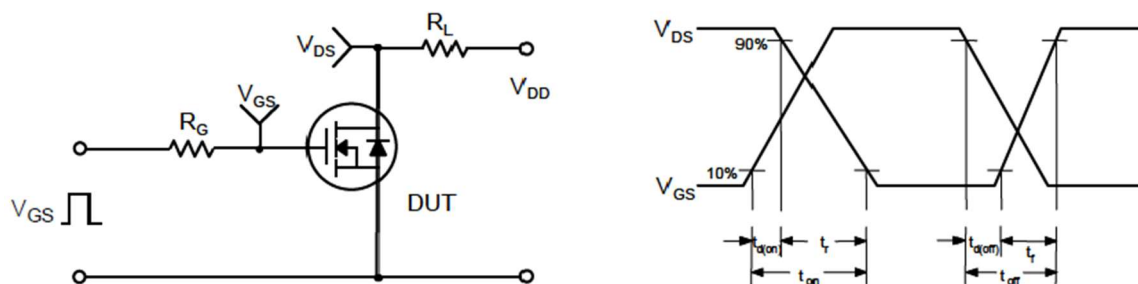


Figure 6. Maximum Safe Operating Area

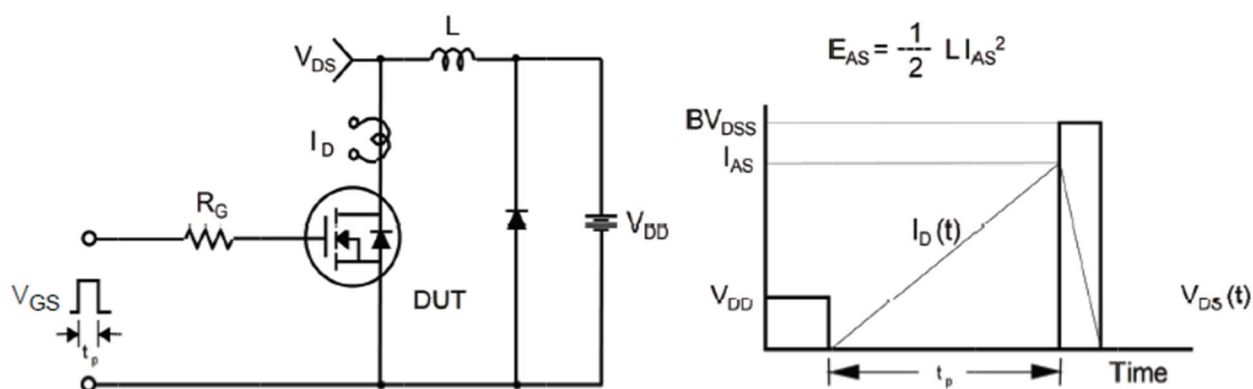
Gate Charge Test Circuit & Waveform



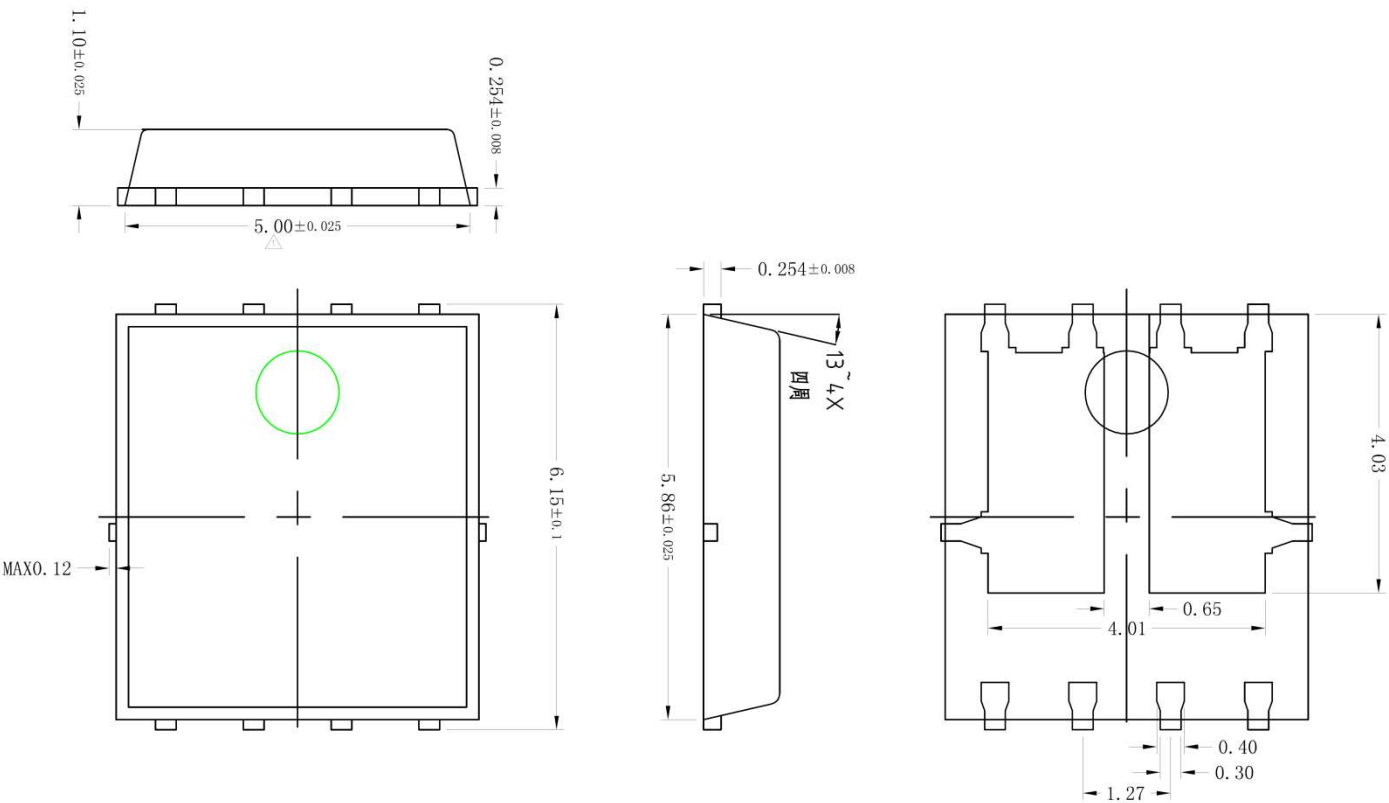
Switching Test Circuit & Waveforms



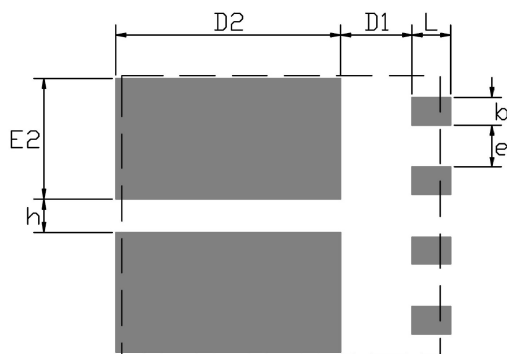
Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions for PDFN5*6



PAD Layout for PDFN5*6



SYMBOL	MILLIMETER
	NOM
b	0.5
e	0.77
D1	1.3
D2	4.1
E2	2.2
L	0.7
h	0.6